RESPONSE UNDER 37 CFR 1.116

EXPEDITED PROCEDURE

THE U.S. PATENT AND TRADEMARK OFFICE

May 24, 2004

Applicants: Tetsuo NISHIKAWA et al

Title : THERMOPLASTIC RESIN COMPOSITION

Group: 1714

Corres. and Mail

BOX AF

Serial No. : 09/973 646

Confirmation No.: 6210

Filed : October 9, 2001

Examiner: Shosho

Atty. Docket No.: Nanjo Case 1

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

## Sir:

Herewith is an amendment in the above-identified application.

- [] Applicant claims small entity status. See 37 CFR 1.27.
- [] The additional filing fee has been calculated as shown below:

	No.	No.	(X)	RATE	()	-	
For I	Filed	Extra	LG Entity		SM Entity	Fee	<u> </u>
Basic Fee			\$770.00		\$385.00		\$
Total Claims	(11 - 2)	20 = 0	x \$ 18.00		x \$ 9.00		
Indep. Claims	(2 -	3 = 0)	x \$ 86.00		x \$ 43.00		
[ ] Multiple Dep.	. Clain	າ	+ \$290.00		+ \$145.00		
* * * TOTAL FILING FEE * * *						\$	0.00

- [X] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by two months. The extension fee is: \$420.00.
- [X] A Check for \$420.00 is enclosed to cover fees.
- [X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

TFC/smd

Terryence F. Chapman Reg. No. 32 549

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 24, 2004.

Terryence F. Chapman

130.10/03